

NJK60R090N8



N-Channel Enhancement Super Junction MOSFET

Voltage: 600 Volts

Current: 32 Ampers

Package: DFN8*8

Features

- NH'S Advanced Super Junction Technology
- Low Rds(on) For Low On-State Loss
- Ultra-Fast Body Diode
- Multilayer Epitaxy For Excellent EMC Features

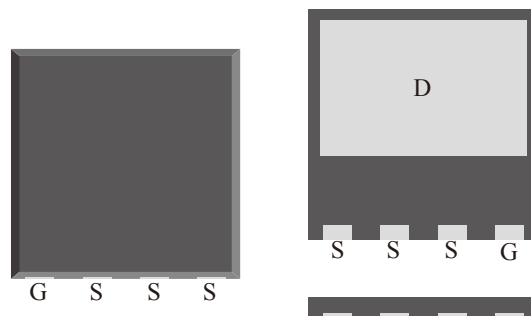
Typical Applications

- Power Factor Correction(PFC)
- LED/LCD/PDP TV And Monitor Lighting
- UPS And Micro Inverter System
- Solar And Renewable

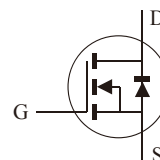
Product Summary

VDS Min.@Tj	600	V
Id Min.@Ta	32	A
RDS(ON)(MAX)@10V	99	mΩ

Diagram:



Polarity:



***100% UIS TESTED**

***100% ΔVDS TESTED**

Absolute Maximum Ratings (Ta=25℃ Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	Ratings	Unit
Drain-Source Voltage		V _{DS}	600	V
Gate-Source Voltage		V _{GS}	±30	V
Continuous Drain Current (Note 1)	Ta= 25 ℃	I _D	32	A
	Ta= 100 ℃		20	
Drain Current-Pulse (Note 1)	Tj< 150 ℃	I _{DM}	95	A
Maximum Power Dissipation Power Dissipation Derating Factor Above 25℃	Ta= 25 ℃	P _D	125	W
	Ta= 100 ℃		50	
Derating Factor		D _F	1.00	W/℃
Avalanche Current,Single Pulse (Note 1)	L= 10.0 mH	I _{AS}	5.6	A
Single Pulse Avalanche Energy (Note 1) Test Circuit & Waveform See Fig.16	L= 10.0 mH IAS= 5.6 A, RG= 10.0 Ω Starting Tj=25 ℃, VG = 10.0 V	E _{AS}	157	mJ

Thermal Characteristics (Ta=25℃ Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	Typ.	Unit
Junction Temperature		T _J	-55 to 150	℃
Storage Temperature Range		T _{STD}	-55 to 150	℃
Thermal Resistance Junction To Ambient With Steady-State	Still Air Environment With Ta=25℃	R _{θJA}	62.5	℃/W
Thermal Resistance Junction-Case With Steady-State	Device Mounted On 1 in2 FR-4 Board With 2oz. Copper	R _{θJC}	1.0	

Notes: 1.Pulse Width Limited By Max. Junction Temperature. (See Fig. 13).

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Electrical Characteristics (Ta=25°C Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	Min.	Typ.	Max.	Unit
Static Off Characteristics						
Drain-Source Breakdown Voltage	VGS=0V,ID=250uA	BV _{DSS}	600	--	--	V
Bvdss Temperature Coefficient	ID=250uA,Reference25℃	ΔBV _{DSS} /ΔT _J	--	0.71	--	V/℃
Drain-Source Leakage Current	VDS= 600 V,VGS=0V	I _{DSS}	--	--	1	uA
Gate-Body Leakage Current	VGS= ±30 V,VDS=0V	I _{GSS}	--	--	±100	nA
Static On Characteristics						
Gate Threshold Voltage	VGS= VDS ID=250uA	V _{GS(TH)}	2.8	3.5	4.2	V
Drain-Source On Resistance	ID= 15.9 A,VGS= 10.0 V	R _{DS(ON)}	--	80	99	mΩ
	ID= 15.9 A,VGS= 4.5 V		--	104	149	
Dynamic Characteristics						
Gate Resistance	VGS=0V,VDS=0V, Freq.=1MHz	R _g	--	1.2	--	Ω
Input Capacitance	VDS= 50 V	C _{iss}	--	2250.0	--	pF
Output Capacitance	VGS= 0 V	C _{oss}	--	58.0	--	pF
Reverse Transfer Capacitance	F= 1 MHZ	C _{rss}	--	3.0	--	pF
Switching Paramters (Test Circuit & Waveform See Fig.14)						
Turn-On Delay Time	VDS= 300 V	t _{d(on)}	--	17.0	--	ns
Turn-On Rise Time	VGS= 10.0 V	t _r	--	10.0	--	ns
Turn-Off Delay Time	RG= 10.0 Ω	t _{d(off)}	--	85.0	--	ns
Turn-Off Rise Time		t _f	--	10.0	--	ns
Gate Charge Paramters (Test Circuit & Waveform See Fig.15)						
Total Gate Charge	VDS= 300 V	Q _g	--	52.0	--	nC
Gate-Source Charge	VGS= 10.0 V	Q _{gs}	--	12.0	--	nC
Gate-Drain Charge	ID= 15.9 A	Q _{gd}	--	22.0	--	nC
Drain-Source Diode Characteristics And Maximum Ratings (Test Circuit & Waveform See Fig.17)						
Max. Diode Forward Cuurent		I _S	--	--	32	A
Max. Pulsed Forward Cuurent		I _{SM}	--	--	95	A
Diode Forward Voltage	ID= 15.9 A,VGS=0V	V _{SD}	--	0.82	1.2	V
Reverse Recovery Time	IS= 15.9 A,di/dt= 100 A/us	t _{rr}	--	340.0	--	ns
Reverse Recovery Charge	VGS= 0.0 V	Q _{rr}	--	5100.0	--	nC
Reverse Recovery Current		I _{RRM}	--	30.0	--	A

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Typical Characteristics Curves

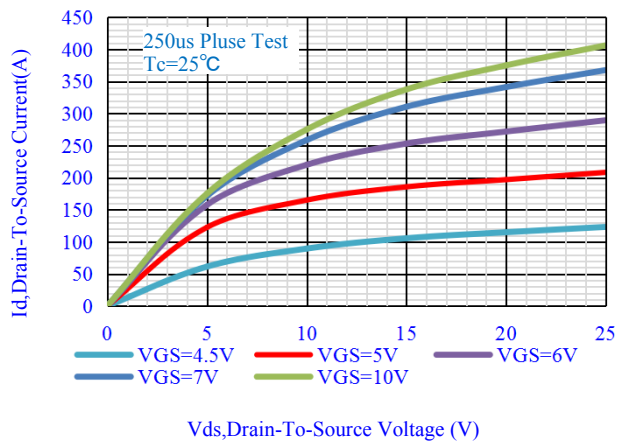


Fig.1-Output Characteristics

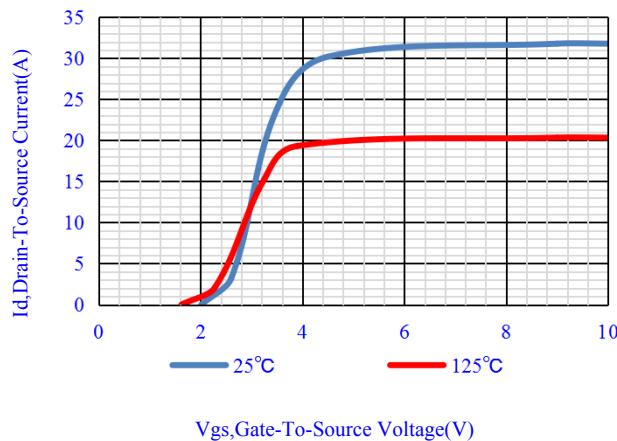


Fig.2-Transfer Characteristics

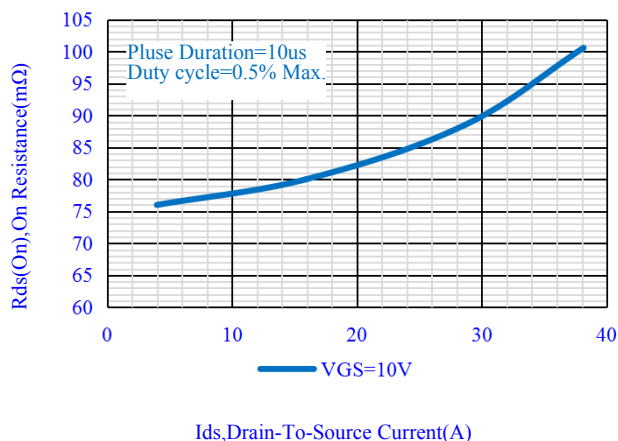


Fig.3-On Resistance Vs. Drain Current

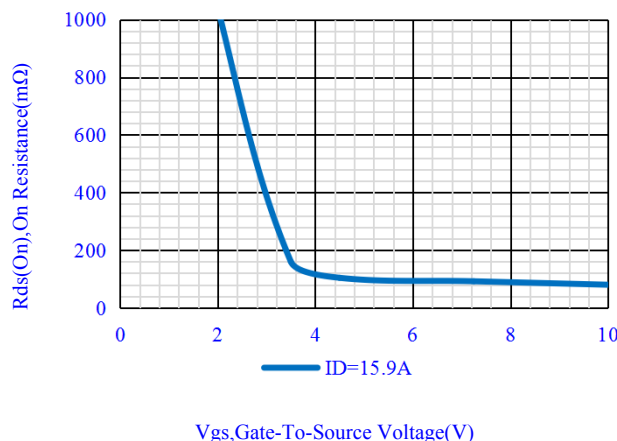


Fig.4-On Resistance Vs. Gate Source Voltage

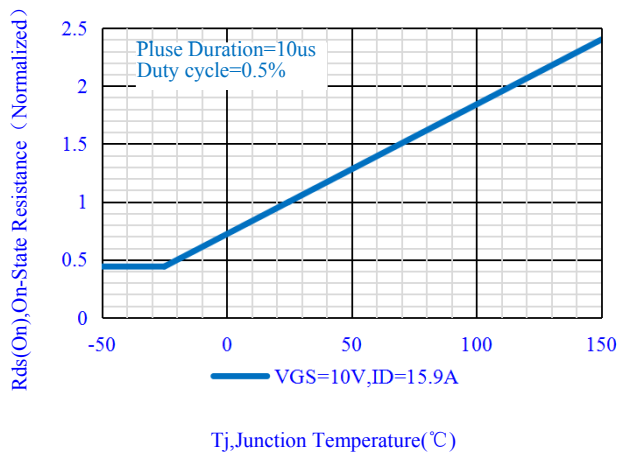


Fig.5-On Resistance Vs. Junction Temperature

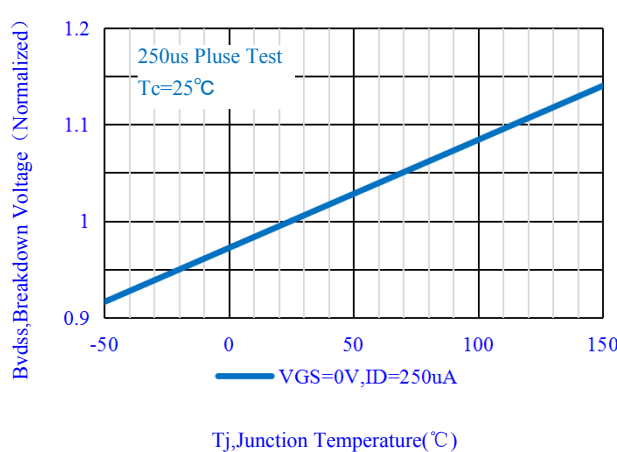


Fig.6-Breakdown Voltage Vs. Junction Temperature

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Typical Characteristics Curves

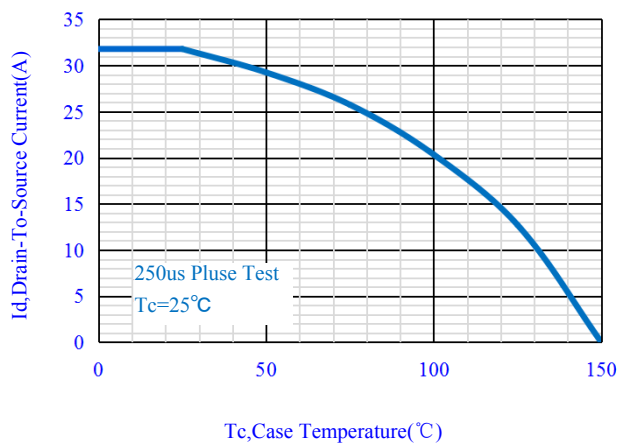


Fig.7-Maximum Continuous Drain Current Vs. Case Temperature

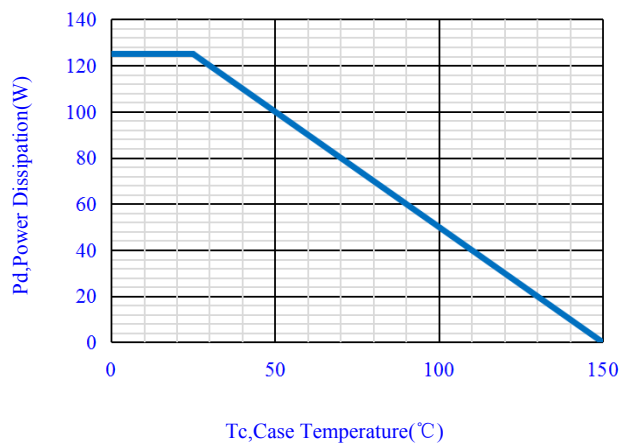


Fig.8-Maximum Power Dissipation Vs. Case Temperature

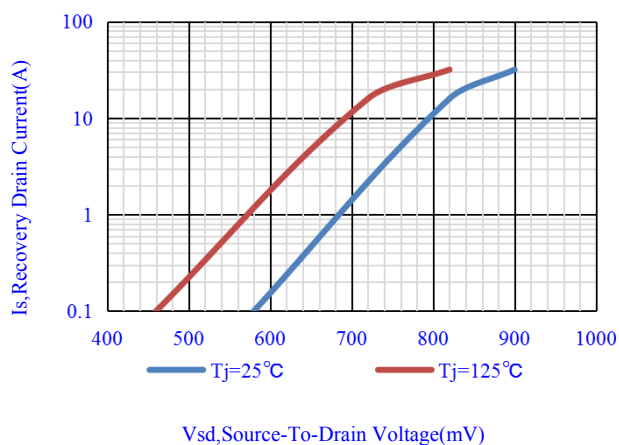


Fig.9-Source-To-Drain Diode Forward Voltage

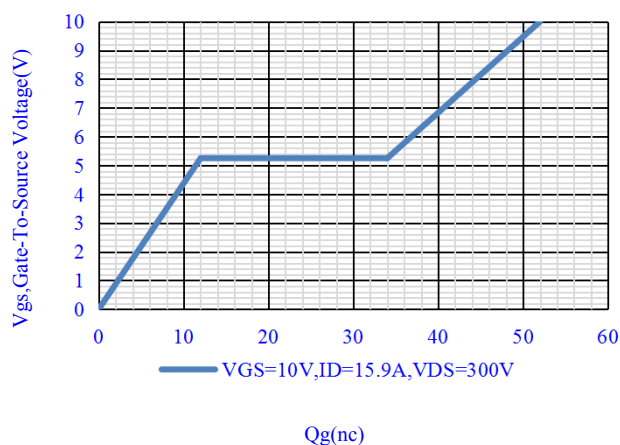


Fig.10-Gate Charge Waveform

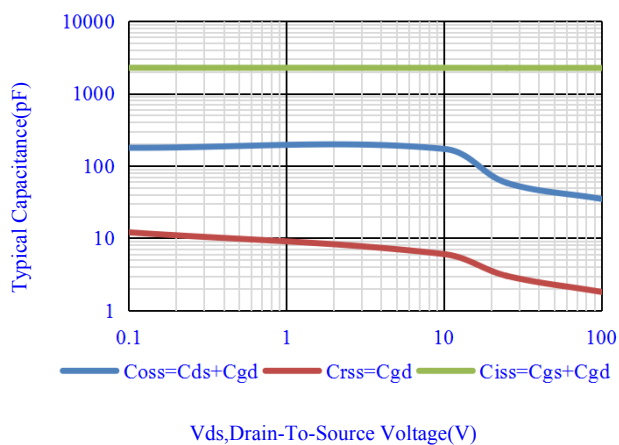


Fig.11-Typical Capacitance Vs. Drain-To-Source Voltage

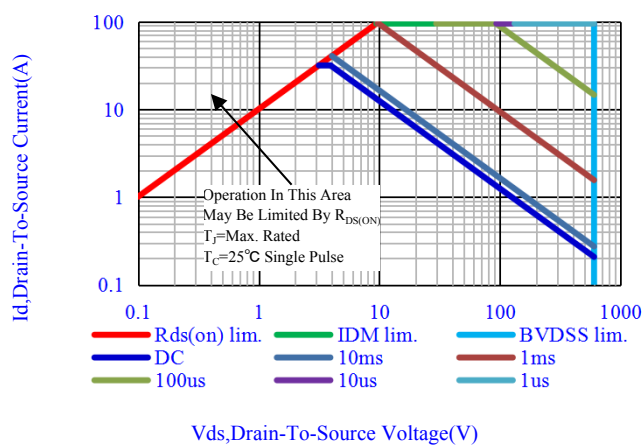


Fig.12-Maximum Safe Operating Area(SOA)

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Typical Characteristics Curves

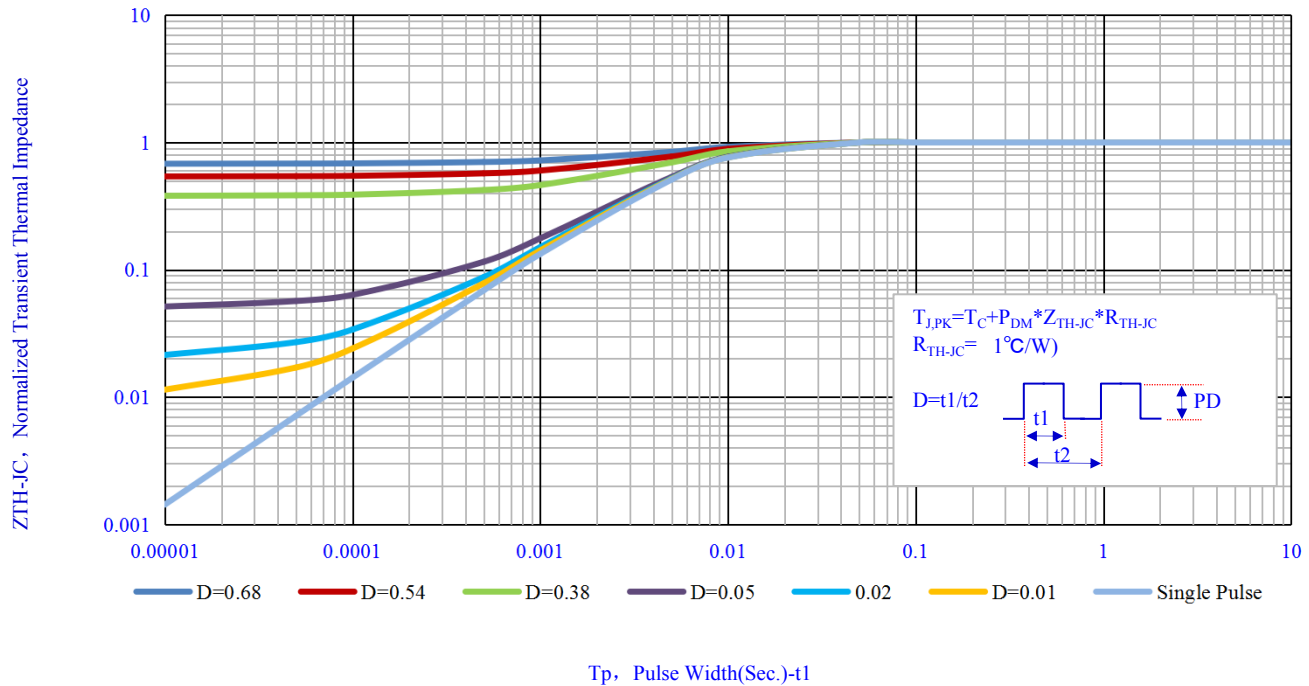


Fig.13- Normalized Maximum Transient Thermal Impedance Vs.Pulse Width

Test Circuit & Waveform

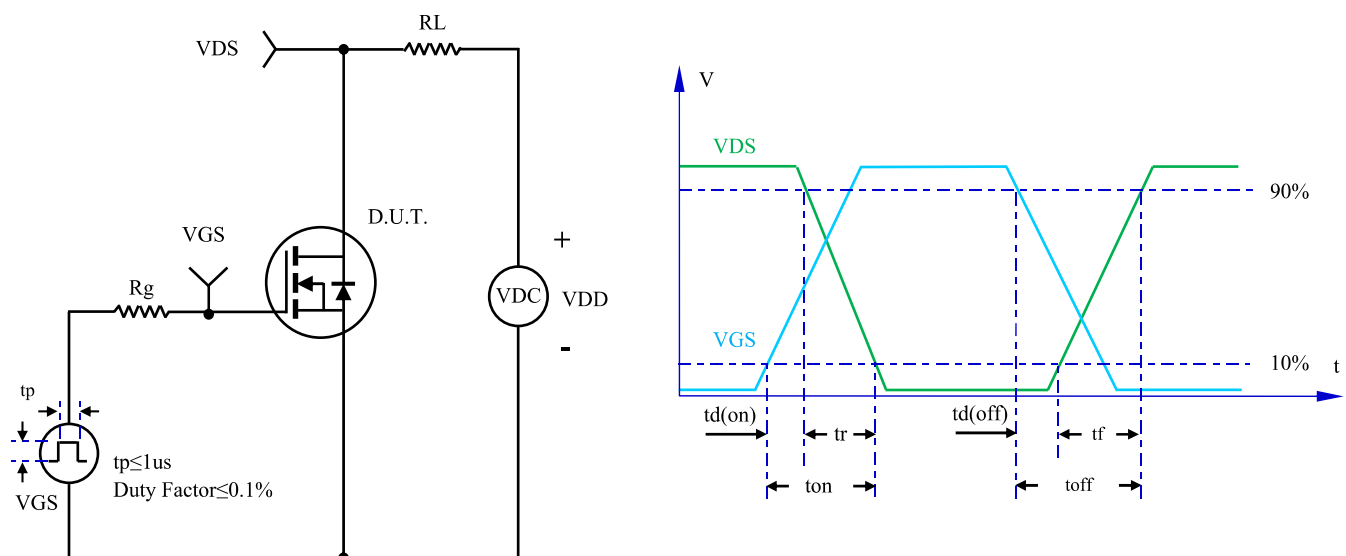


Fig.14- Resistive Switching Test Circuit & Waveform

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Test Circuit & Waveform

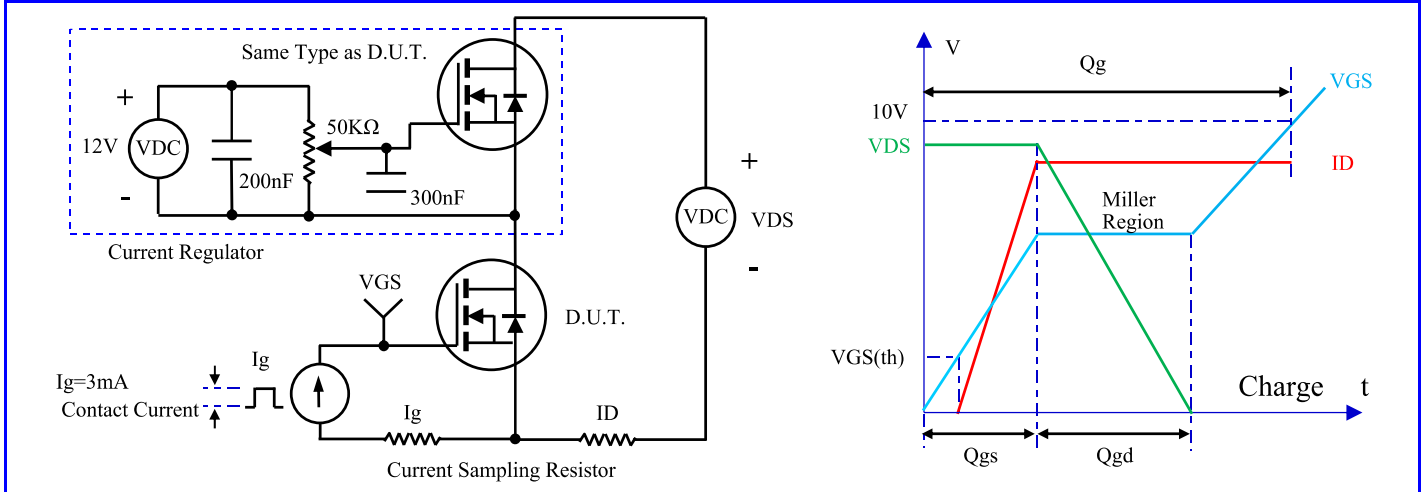


Fig.15- Gate Charge Test Circuit & Waveform

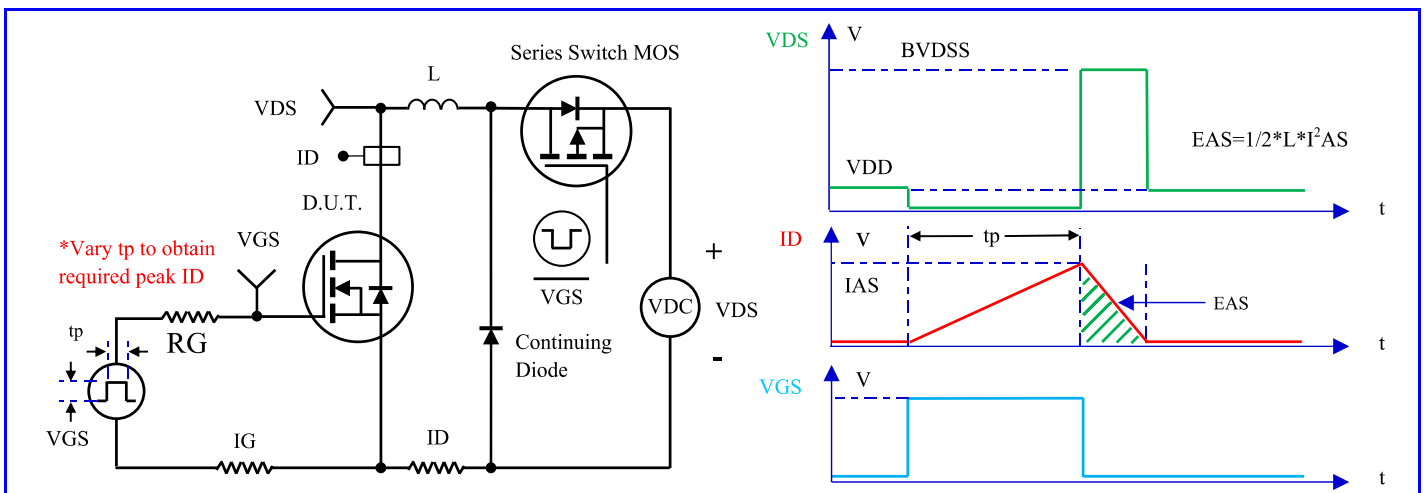


Fig.16- Unclamped Inductive Switching (UIS) Test Circuit & Waveform

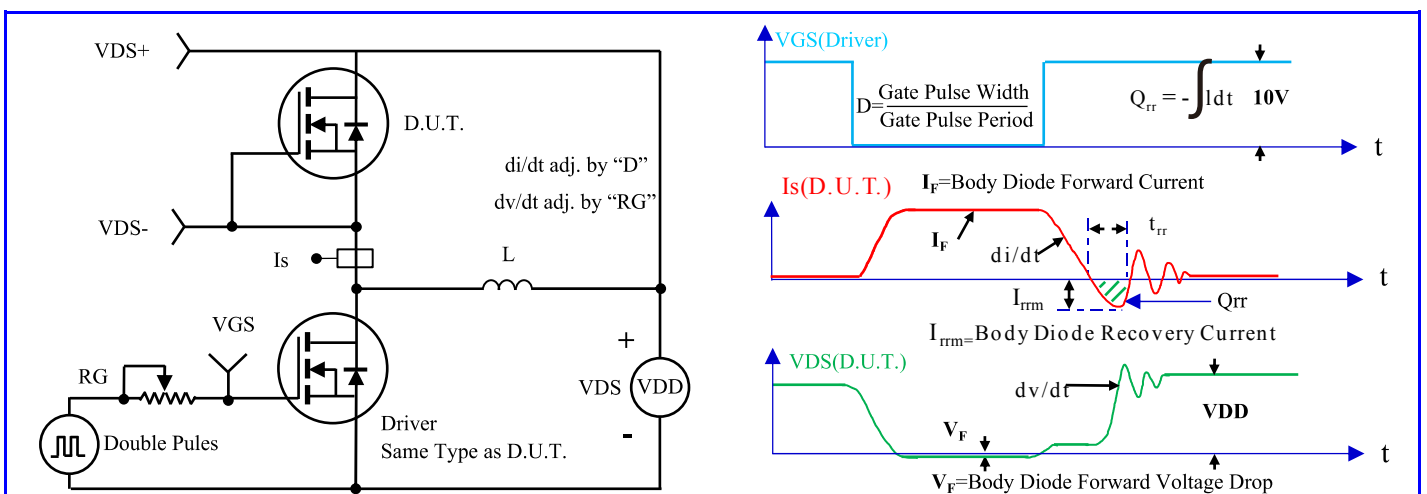


Fig.17- Diode Recovery Test Circuit & Waveform

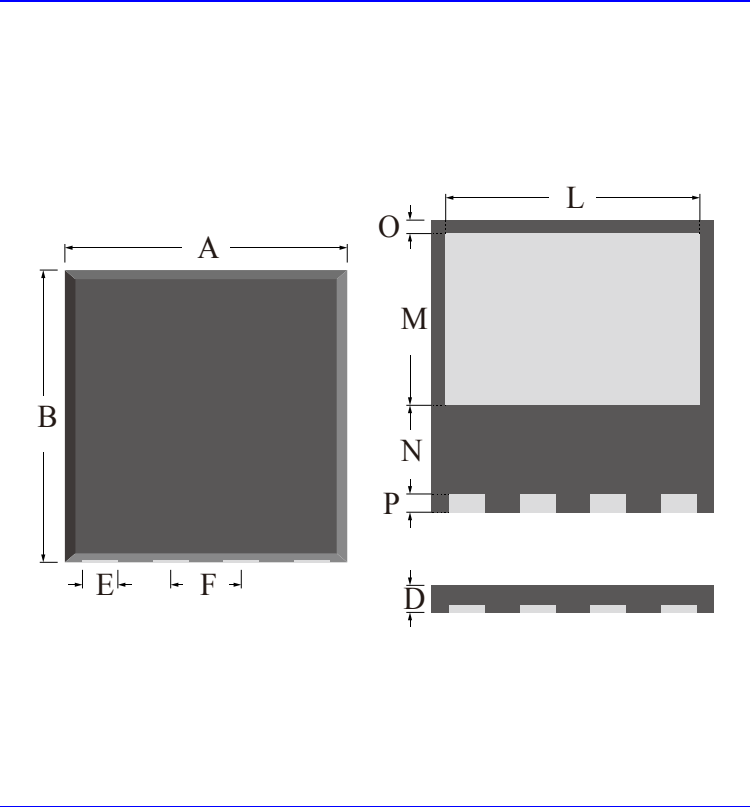
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OUTLINE DRAWINGS

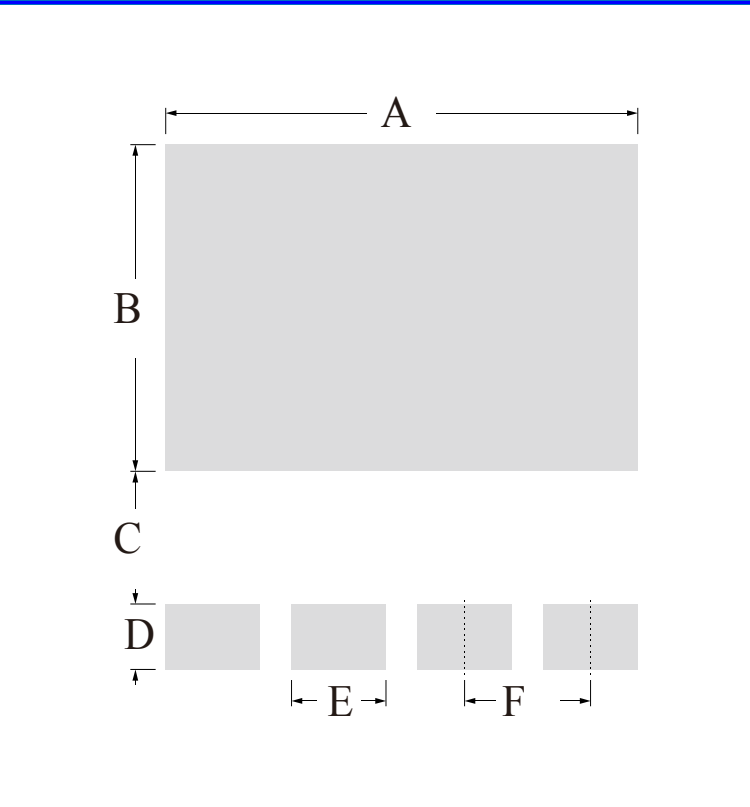
DFN8*8



OUTLINE DIMENSIONS						
Dim.	Milimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	7.00	-	9.00	0.2756	-	0.3543
B	7.00	-	9.00	0.2756	-	0.3543
D	0.55	-	1.15	0.0217	-	0.0453
E	0.70	-	1.30	0.0276	-	0.0512
F	1.35	-	2.55	0.0531	-	0.1004
L	6.70	-	7.70	0.2638	-	0.3031
M	4.20	-	5.20	0.1654	-	0.2047
N	2.12	-	3.32	0.0835	-	0.1307
O	0.17	-	0.57	0.0067	-	0.0224
P	0.35	-	0.65	0.0138	-	0.0256

RECOMMEDND LAYOUT DRAWINGS

DFN8*8



OUTLINE DIMENSIONS						
Dim.	Milimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	-	7.50	-	-	0.2953	-
B	-	5.00	-	-	0.1969	-
C	-	2.00	-	-	0.0787	-
D	-	1.00	-	-	0.0394	-
E	-	1.50	-	-	0.0591	-
F	-	1.95	-	-	0.0768	-

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MARKING INFORMATION



MARKING INSTRUCTIONS

NH=Niuhan Trademark

FF=Product Line Code,According To Actual Changes

YWW=Date Code,According To Actual Changes

LLWWF=Inernal Code,According To Actual Changes

NJK60R090N8=Model

PACKING INFORMATION

Package Type	Package Code	Product Weight Approx(g/Pcs)	Package Method	Quantity (Pcs/Min. Pack.)	Quantity (Pcs/Inner Box)	Quantity (Pcs/Carton)
DFN8*8	P1	0.23	13" Reel	5000	10000	50000

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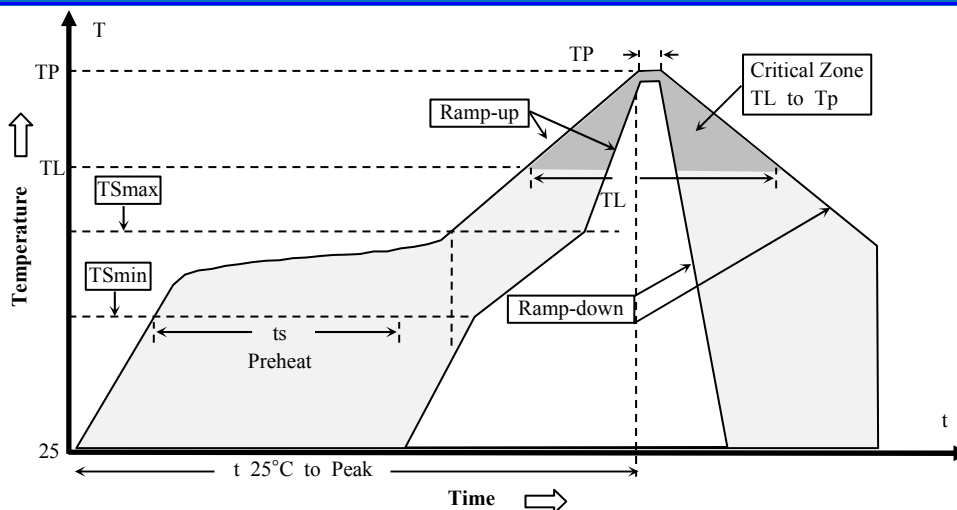
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Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T _{smax} to T _p)	3°C/second max.	3°C/second max.
Preheat -Temperature Min(T _S min) -Temperature Max(T _S max) -Time(t _s min to t _s max)	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: -Temperature (T _L) - Time (t _L)	183°C 60-150 seconds	217°C 60-150 seconds
Peak Temperature(T _P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

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